

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7309724

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GER-CHIH CHOU	05/03/2022
CHIH-WEI CHANG	05/03/2022
LI-JUN GU	05/03/2022
CHUN-CHI YU	05/03/2022
FU-CHIN TSAI	05/03/2022
RECEIVING PARTY DATA	
Name:	REALTEK SEMICONDUCTOR CORPORATION
Street Address:	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	Taiwan ROC
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17735142
CORRESPONDENCE DATA	
Fax Number:	(703)880-7487
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-639-0151
Email:	assignment@WPAT.COM
Correspondent Name:	WPAT, PC INTELLECTUAL PROPERTY ATTORNEYS
Address Line 1:	8230 BOONE BLVD, SUITE 405
Address Line 4:	VIENNA, VIRGINIA 22182
ATTORNEY DOCKET NUMBER:	16313-483
NAME OF SUBMITTER:	JUSTIN KING
SIGNATURE:	/Justin King/
DATE SIGNED:	05/03/2022
Total Attachments: 2	
source=a#page1.tif	

ASSIGNMENT

WHEREAS, I(we), GER-CHIH CHOU, CHIH-WEI CHANG, LI-JUN GU, CHUN-CHI YU, and FU-CHIN TSAI whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

Memory system and memory access interface device thereof

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent /Utility Patent is executed on even date herewith unless at least one of the following is checked:

- ☐ United States Design Patent was
☐ executed on:
☐ filed on: Serial No.:
☐ established by PCT International Patent Application No.: filed: designating the
United States of America
☐ issued on _____ as U.S. Patent No.: _____

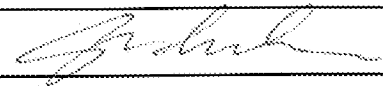
WHEREAS, **REALTEK SEMICONDUCTOR CORPORATION** whose post office address is **No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)** hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States and its territorial possessions;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application for the full term or terms for which the same may be granted, including all priority rights under any International Convention.

ASSIGNOR further covenants that no assignments, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment;

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance, litigation and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR NAME GER-CHIH CHOU	Address 6291 Dial Way San Jose, CA95129
Signature of Assignor 	Date of Signature May 3, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME CHIH-WEI CHANG	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Chih wei Chang</i>	Date of Signature May 3, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME LI-JUN GU	Address No. 128, West Shenhua Road, Suzhou Industrial Park, Suzhou 215021, Jiangsu Province, China (P.R.C.)
Signature of Assignor <i>Li Jun Gu</i>	Date of Signature May 3, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME CHUN-CHI YU	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Chun-Chi Yu</i>	Date of Signature May 3, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)

ASSIGNOR NAME FU-CHIN TSAI	Address No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)
Signature of Assignor <i>Fuchin Tsai</i>	Date of Signature May 3, 2022
Name of Witness (optional)	Name of Witness (optional)
Signature of Witness (optional)	Signature of Witness (Optional)